



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of

KITANO et al

Atty. Ref.: 160-513; Confirmation No.

Appl. No. 10/594,422

TC/A.U.

Filed: September 26, 2006

Examiner: unknown

For: NITRIDE SEMICONDUCTOR LASER ELEMENT

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December 4, 2006

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

SUBMISSION OF INTERNATIONAL PRELIMINARY REPORT ON PATENTABILITY

Attached is a copy of the International Preliminary Report on Patentability (English version) mailed October 5, 2006 and issued in the underlying International patent application.

Please consider this information when examining the above-identified u.s. national stage application.

Respectfully submitted,

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From the INTERNATIONAL BUREAU

PCT

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OF THE INTERNATIONAL PRELIMINARY REPORT
ON PATENTABILITY
(CHAPTER I OR CHAPTER II
OF THE PATENT COOPERATION TREATY)

(PCT Rules 44bis.3(c) and 72.2)

To:

SUZUYE, Takehiko c/o SUZUYE & SUZUYE 1-12-9, Toranomon Minato-ku, Tokyo 105-0001 JAPON

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SUZUYE & SUZUYE

Date of mailing (day/month/year)
05 October 2006 (05.10.2006)

Applicant's or agent's file reference 05S0188P

International application No. PCT/JP2005/004249

IMPORTANT NOTIFICATION

International filing date (day/month/year)
10 March 2005 (10.03.2005)

Applicant

Nichia Corporation et al

1. 7	[ransmittal	of the	translation	to	the ap	oblicant.
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The International Bureau transmits herewith a copy of the English translation of the international preliminary report on patentability (Chapter I).

The International Bureau transmits herewith a copy of the English translation of the international preliminary report on patentability (Chapter II).

2. Transmittal of the copy of the translation to the designated or elected Offices.

The International Bureau notifies the applicant that copies of that translation have been transmitted to the following designated or elected Offices requiring such translation:

None

The following designated or elected Offices, having waived the requirement for such a transmittal at this time, will receive copies of that translation from the International Bureau only upon their request:

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3. Reminder regarding translation into (one of) the official language(s) of the elected Office(s).

The applicant is reminded that, where a translation of the international application must be furnished to an elected Office, that translation must contain a translation of any annexes to the international preliminary report on patentability (Chapter II).

It is the applicant's responsibility to prepare and furnish such translation directly to each elected Office concerned within the applicable time limit (Rule 74.1). See Volume II of the PCT Applicant's Guide for further details.

The International Bureau of WIPO 34, chemin des Colombettes 1211 Geneva 20, Switzerland

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PATENT COOPERATION TREATY

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INTERNATIONAL PRELIMINARY REPORT ON PATENTABILITY

(Chapter I of the Patent Cooperation Treaty)

(PCT Rule 44bis)

See item 4 below

FOR FURTHER ACTION

	national application No. JP2005/004249	International filing date (day/m 10 March 2005 (10.03.2005)		Priority date (day/month/year) 26 March 2004 (26.03.2004)
	national Patent Classification (8th relevant information in Form F	h edition unless older edition ind PCT/ISA/237	icated)	
Appli Nichi	cant a Corporation			
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1.	This international preliminary International Searching Author		I) is issued by the I	nternational Bureau on behalf of the
2.	This REPORT consists of a to	tal of 6 sheets, including this cov	er cheet	
		-		arching Authority should be read as a reference
		y report on patentability (Chapter		
3.	This report contains indication	is relating to the following items:		
	Box No. I	Basis of the report		
	Box No. II	Priority		
	Box No. III	Non-establishment of opiniapplicability	on with regard to no	ovelty, inventive step and industrial
	Box No. IV	Lack of unity of invention		
	Box No. V	Reasoned statement under applicability; citations and		egard to novelty, inventive step or industrial rting such statement
	Box No. VI	Certain documents cited		
	Box No. VII	Certain defects in the intern	ational application	
	Box No. VIII	Certain observations on the	international applic	cation
4.	The International Bureau will o	communicate this report to design	nated Offices in acc	cordance with Rules 44bis.3(c) and 93bis.1 but
	not, except where the applicant date (Rule 44bis .2).	t makes an express request under	Article 23(2), before	ore the expiration of 30 months from the priority
		ſ	Date of issuance of	this report
			26 September 200	-
The International Bureau of WIPO 34, chemin des Colombettes 1211 Geneva 20, Switzerland			Authorized officer	Yoshiko Kuwahara

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Applicant's or agent's file reference 05S0188P

PATENT COOPERATION TREATY

From th INTER		NAL SEARCHI	NG AUTHOR	ITY		W.C.	
То:				·		PCT PTON	
						RITTEN OPINION OF THE TONAL SEARCHING AUTHORITY	
						(PCT Rule 43bis.1)	
					Date of mailing (day/month/year)		
<u>-</u> -		gent's file referen	ice	FOR FURTHER ACTION			
	30188					See paragraph 2 below	
	-	plication No. 2005/004	249	International filing date (day/month/year)	Priority date (day/month/year) 26.03.2004	
Internat	tional Pa	tent Classification	n (IPC) or both	national classification an	d IPC		
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Applica	ant						
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1.	This o	ninion contains i	ndications relat	ing to the following items			
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	Box No. III Non-establishment of opinion with regard				and to noverty, inventive step and industrial applicability		
	Box No. IV Lack of unity of invention Reasoned statement under Rule 43bis.1(a applicability; citations and explanations a			etement under Rule 43 <i>bis</i> .	1(a)(i) with regard to novelty, inventive step or industrial		
		Box No. VI	Certain docu	_	is supporting such stat	ement	
		Box No. VII			li aati an		
	Ħ	Box No. VIII		cts in the international app			
		Box No. VIII	Certain obse	rvations on the internation	iai application		
2.	FURT	HER ACTION					
	Internathan th	ational Preliminar his one to be the	ry Examining A IPEA and the	Authority ("IPEA") except	t that this does not app the International Bure	l be considered to be a written opinion of the ply where the applicant chooses an Authority other eau under Rule 66.1 bis(b) that written opinions of	
	writter	reply together.	where approp	considered to be a written riate, with amendments, of 22 months from the pri	before the expiration	the applicant is invited to submit to the IPEA a of 3 months from the date of mailing of Form expires later.	
	For fur	ther options, see	Form PCT/ISA	A/220.			
3.	For fu	ther details, see r	notes to Form F	CT/ISA/220.			
Name a	nd mailii	ng address of the	ISA/JP		Authorized officer		
			-				
Facsimi)	le No.				Telephone No.		

International application No.

PCT/JP2005/004249

Box	No. I	Basis of this opinion
1.	With	regard to the language, this opinion has been established on the basis of the international application in the language in which it was, unless otherwise indicated under this item.
		This opinion has been established on the basis of a translation from the original language into the following language
	-	Rule 12.3 and 23.1(b)). which is the language of a translation furnished for the purposes of international search (under
2.	With inver	regard to any nucleotide and/or amino acid sequence disclosed in the international application and necessary to the claimed nation, this opinion has been established on the basis of:
	a.	type of material
		a sequence listing
		table(s) related to the sequence listing
	b.	format of material
		in written format
		in computer readable form
	c.	time of filing/furnishing
		contained in the international application as filed.
		filed together with the international application in computer readable form.
		furnished subsequently to this Authority for the purposes of search.
3.		In addition, in the case that more than one version or copy of a sequence listing and/or table(s) relating thereto has been filed or furnished, the required statements that the information in the subsequent or additional copies is identical to that in the application as filed or does not go beyond the application as filed, as appropriate, were furnished.
4.	Addi	tional comments:
		•

International application No.
PCT/JP2005/004249

Box	No. V Reasoned statement citations and expla	nt under Ru anations sup	ule 43bis.1(a)(i) with regard to novelty, inventive step or industrial applicability; oporting such statement	
1.	Statement			
	Novelty (N)	Claims	1-14	YES
		Claims		NO
	Inventive step (IS)	Claims		YES
		Claims	1-14	NO
	Industrial applicability (IA)	Claims	1-14	YES
		Claims	•	NO

2. Citations and explanations:

(1) Claims 1-3

Document 1 cited in the ISR describes a nitride semiconductor laser element wherein an n-type nitride semiconductor layer, an activation layer and a p-type nitride semiconductor layer are stacked, and a ridge-shaped stripe is provided in the p-type nitride semiconductor layer.

Document 1: JP, 2001-210914, A (Nichia Chemical Industries, Ltd.), 3 August, 2001 (03.08.01), paragraphs [0013]-[0020], Fig. 1 (Family: none)

The above nitride semiconductor laser element is such that a rich layer containing plenty of aluminum and boron is formed near the surface of the side of a ridge-shaped stripe from the surface to the inside, and this is done so as to improve the insulation of the element. Fig. 6 of document 1 describes a nitride semiconductor laser element in which the rich layer is not formed, and a ridge-shaped stripe which was well known in prior art is provided.

A semiconductor element including a nitride semiconductor laser element requires speedup according to its usage, and to comply with this requirement, a technique for reducing the element capacity in an area around a wave guide region is known.

For example, document 2 cited in the ISR describes that an ion is implanted into the semiconductor layer in a peripheral area separated from the wave guide region, and the electric resistance of that part is made high to reduce the depletion layer capacity of the pn-junction.

Document 2: JP, 5-190980, A (The Furukawa Electric Co., Ltd.), 30 July, 1993 (30.07.93), paragraphs [0005]-[0006], Fig. 1 (Family: none)

In a nitride semiconductor laser element which was well known in prior art wherein an n-type nitride semiconductor layer, an activation layer, and a p-type nitride semiconductor layer are stacked, and a ridge-shaped stripe is provided in the p-type nitride semiconductor layer, a person skilled in the art could have easily conceived of forming such a constitution as that of the subject matters of claims 1, 2 or 3 in order to implement speedup by implanting an ion into the semiconductor layer in a peripheral area separated from a wave guide region, and reducing the depletion layer capacity of the pn-junction.

(2) Claim 4

Described below is the result of studies of an insulating film. Any other matter is as studied in (1) above.

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Box No. V

Reasoned statement under Rule 43bis.1(a)(i) with regard to novelty, inventive step or industrial applicability; citations and explanations supporting such statement

In the semiconductor laser element described in document 1, an insulating film is formed on the side of a ridge stripe formed in a p-type semiconductor layer and on the surface of a p-type semiconductor layer.

Document 3 cited in the ISR describes that a first insulating film (301) is formed on the side of a ridge stripe formed in a p-type semiconductor layer and on the surface of a p-type semiconductor layer, and a second insulating film (302) which covers part of the first insulating film and extends up to the side of a wave guide region is formed.

The first insulating film corresponds to the embedded insulating film described in claim 4, and the second insulating film corresponds to the protective insulating film described in claim 4.

Document 3: JP, 2002-237661, A (Nichia Chemical Industries, Ltd.), 23 August, 2002 (23.08.02), paragraph [0062], Fig. 2 (Family: none)

A person skilled in the art could have easily applied a technique for forming the insulating film in the nitride semiconductor laser element described in document 3 instead of the insulating film in the nitride semiconductor laser element described in document 1 to form such a constitution as that of the subject matter of claim 4.

(3) Claim 5

The peak value of impurity concentration of an insulation region formed by ion implantation is set as required according to the degree of dielectric strength. For example, document 4 cited in the ISR describes that the carbon concentration of the insulation region formed by the ion implantation of carbon is about 1.0×10^{20} cm⁻³.

Document 4: JP, 2003-264346, A (Sanyo Electric Co., Ltd.), 19 September, 2003 (19.09.03), paragraph [0052] (Family: none)

Judging from this fact, no special meaning can be found in setting the impurity concentration of the insulation region to a level of 1×10^{18} to 5×10^{21} atms/cm³ described in claim 5.

(4) Claim 6

The range in the depth direction of an impurity concentration distribution in an insulation region is determined depending upon up to which semiconductor layer among the semiconductor layers constituting a semiconductor laser element is insulated, and a person skilled in the art could have easily set it as required, so no special meaning can be found in setting said range to a level of 20 nm to 1 µm from the surface described in claim 6.

Meanwhile, according to the description of paragraphs [0055]-[0057], the range in the depth direction of an impurity concentration distribution of an insulation region in the nitride semiconductor laser element described in document 4 is about 0.15 μ m or 0.23 μ m.

(5) Claims 7-8

Document 3 discloses that a p-side ohmic electrode (201) (which corresponds to a first electrode described in claims 7 and 8) formed on a p-type semiconductor layer is formed so as to cover part of a first insulating film (301), and a p-side pad electrode (202) comes into contact with the p-side ohmic electrode and covers part of a second insulating film.

In consideration of an electric current channel in a semiconductor laser element, a person skilled in the art could have easily conceived of including an embedded insulating film and the

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Box No. V

Reasoned statement under Rule 43bis.1(a)(i) with regard to novelty, inventive step or industrial applicability; citations and explanations supporting such statement

lower-part region of the first electrode or pad electrode when an insulation region is provided.

(6) Claims 9 and 14

When the element capacity in a peripheral area of a wave guide region is reduced to implement speedup as described in document 2, what degree of response is required therefor can be set as required by a person skilled in the art, and no special meaning can be found in setting the response to the input of a pulse driving electric current to 1 ns or less as described in claim 9 or 14.

(7) Claim 10

When the element capacity in a peripheral area of a wave guide region is reduced as described in (1) above, what degree of withstand voltage the insulation region for reducing the element capacity should have can be set as required by a person skilled in the art, and no special meaning can be found in setting the withstand voltage to 10 V or more.

(8) Claims 11-13

As a technique for reducing the element capacity of a semiconductor laser element, it is a well-known technique to make at least part of a second electroconductive type semiconductor layer in the depth direction a first electroconductive type semiconductor layer in a peripheral area separated from the wave guide region. For example, document 5 cited in the ISR describes that an n-type current blocking area (4b) is formed on a p-type upper first clad layer.

Document 5: JP, 63-222488, A (Rohm Co., Ltd.), 16 September, 1988 (16.09.88), page 2, upper left column, lines 4-9, page 2, lower right column, line 16 to page 3, upper left column, line 4, Figs. 1(D), 7(B) (Family: none)

It is clear as disclosed in Fig. 1(D) of document 5 that if an n-type region is provided in part of a p-type semiconductor layer, the p-type semiconductor layer is of a pnpn structure, and it is clear as disclosed in Fig. 7(B) of document 5 that if an n-type region is provided from the surface of a p-type semiconductor layer, the p-type semiconductor layer is of a npn structure.